

**What is claimed is:**

1           1. A heat dissipation structure for a backlight  
2 module comprising a circuit board having a through hole  
3 with a light emitting diode (LED) corresponding thereto,  
4 disposed on one side of the circuit board, comprising:

5           a heat conducting portion thermo-conductively  
6           connected to the LED and positioned in the  
7           through hole;

8           a thermal conductive element disposed between the  
9           heat conducting portion and the LED; and

10          a heat dissipating portion thermo-conductively  
11          connected to the heat conducting portion.

1           2. The heat dissipation structure as claimed in  
2 claim 1, wherein the thermal conductive element contacts  
3 the heat conducting portion and the LED.

1           3. The heat dissipation structure as claimed in  
2 claim 2, wherein the thermal conductive element comprises  
3 a thermal conductive pad.

1           4. The heat dissipation structure as claimed in  
2 claim 2, wherein the thermal conductive element comprises  
3 a layer of thermal conductive paste.

1           5. The heat dissipation structure as claimed in  
2 claim 1, wherein the heat conducting portion and the heat  
3 dissipating portion are integrally formed.

1           6.    The heat dissipation structure as claimed in  
2    claim 1, wherein the heat conducting portion comprises a  
3    heat conducting column.

1           7.    The heat dissipation structure as claimed in  
2    claim 1, wherein the heat dissipation portion comprises a  
3    heat dissipation plate.

1           8.    The heat dissipation structure as claimed in  
2    claim 1, wherein the heat conducting portion and the heat  
3    dissipation portion are made of metal.

1           9.    The heat dissipation structure as claimed in  
2    claim 1, wherein the heat conducting portion and the heat  
3    dissipation portion are made of engineering plastic.

1           10.   A backlight module, comprising:

2           a housing;

3           a circuit board having a plurality of through holes  
4           and disposed on the housing;

5           a plurality of light emitting diodes (LEDs)  
6           corresponding to the through holes and disposed  
7           on and electrically connected to the circuit  
8           board;

9           a plurality of heat conducting portions thermo-  
10          conductively connected to the LEDs and disposed  
11          in the through holes;

12          a plurality of thermal conductive elements disposed  
13          between the LEDs and the heat conducting  
14          portions; and

15           at least one heat dissipation portion thermo-  
16           conductively connected to the heat conducting  
17           portions and positioned between the circuit  
18           board and the housing.

1           11. The backlight module as claimed in claim 10,  
2           wherein the heat dissipation portion contacts the  
3           housing.

1           12. The backlight module as claimed in claim 10,  
2           wherein the thermal conductive element contacts the heat  
3           conducting portion and the LED.

1           13. The backlight module as claimed in claim 12,  
2           wherein the thermal conductive element comprises a  
3           thermal conductive pad.

1           14. The backlight module as claimed in claim 12,  
2           wherein the thermal conductive element comprises a layer  
3           of thermal conductive paste.

1           15. The backlight module as claimed in claim 10,  
2           wherein the heat conducting portion and the heat  
3           dissipating portion are integrally formed.

1           16. The backlight module as claimed in claim 10,  
2           wherein the heat conducting portion comprises a heat  
3           conducting column.

1           17. The backlight module as claimed in claim 10,  
2           wherein the heat dissipation portion comprises a heat  
3           dissipation plate.

1           18. The backlight module as claimed in claim 10,  
2       wherein the heat conducting portion and the heat  
3       dissipation portion are made of metal.

1           19. The backlight module as claimed in claim 10,  
2       wherein the heat conducting portion and the heat  
3       dissipation portion are made of engineering plastic.